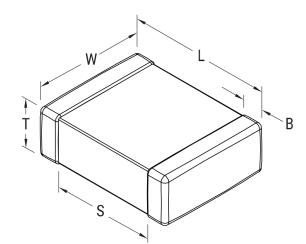


C0805F104K5RALTU

Aliases (C0805F104K5RAL7800)

SMD Comm X7R FO, Ceramic, 0.1 uF, 10%, 50 VDC, X7R, SMD, MLCC, Open Mode, Temperature Stable, 0805



Click here for the 3D model.

Chip Size 0805 L 2mm +/-0.2mm W 1.25mm +/-0.2mm T 1.25mm +/-0.15mm S 0.75mm MIN B 0.5mm +/-0.25mm	Dimensions	
W 1.25mm +/-0.2mm T 1.25mm +/-0.15mm S 0.75mm MIN	Chip Size	0805
T 1.25mm +/-0.15mm S 0.75mm MIN	L	2mm +/-0.2mm
S 0.75mm MIN	W	1.25mm +/-0.2mm
	Т	1.25mm +/-0.15mm
B 0.5mm +/-0.25mm	S	0.75mm MIN
	В	0.5mm +/-0.25mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2500

General Information		
Series	SMD Comm X7R FO	
Style	SMD Chip	
Description	SMD, MLCC, Open Mode, Temperature Stable	
Features	Open Mode, Temperature Stable	
RoHS	No	
Prop 65	A WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov.	
SCIP Number	fb6df79c-d228-431c-9d46-4cd25ad28433	
Termination	Lead (SnPb)	
Marking	No	
AEC-Q200	No	
Component Weight	21 mg	
Shelf Life	78 Weeks	
MSL	1	

Specifications	
Capacitance	0.1 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5%1kHz1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	10 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

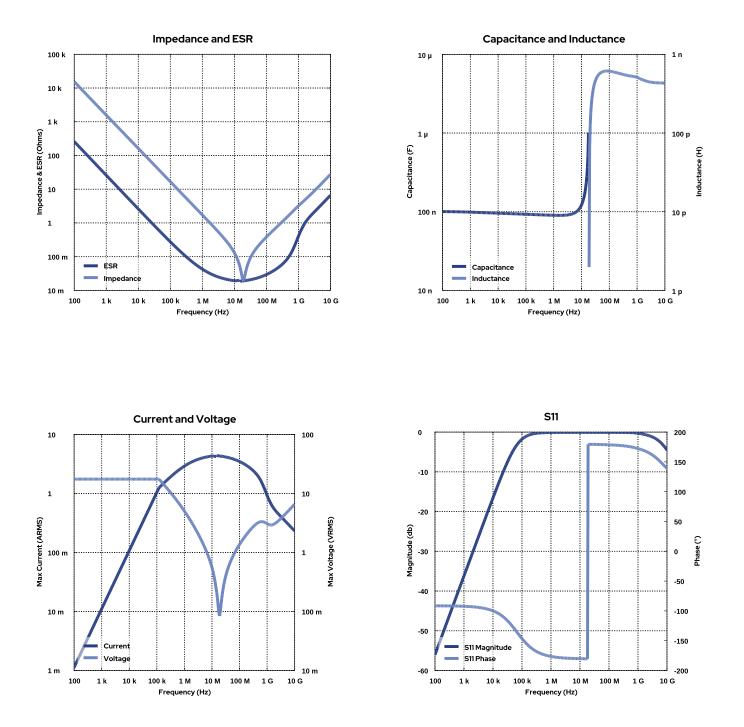


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Simulations

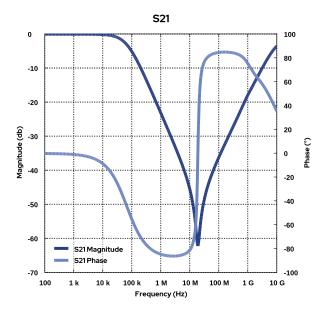
For the complete simulation environment please visit K-SIM.

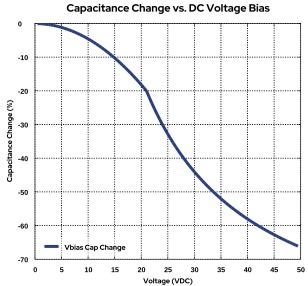




C0805F104K5RALTU Aliases (C0805F104K5RAL7800)

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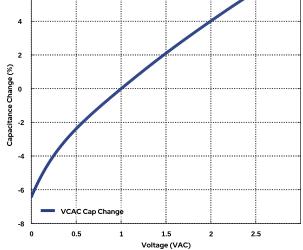




Capacitance Change versus Temperature 2 0 -2 Capacitance Change (%) -4 -6 -8 -10 Temp Çap Change -12 -60 -40 -20 0 20 40 60 80 100 120 140

Temperature (C)

Capacitance Change versus AC Voltage



6



C0805F104K5RALTU

Aliases (C0805F104K5RAL7800)

SMD Comm X7R FO, Ceramic, 0.1 uF, 10%, 50 VDC, X7R, SMD, MLCC, Open Mode, Temperature Stable, 0805

These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.
- The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
- The effects shown herein are based on measured data from a multiple part sample of the parts in question.
- Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance. The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages generated at any other
- harmonics.
- Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.